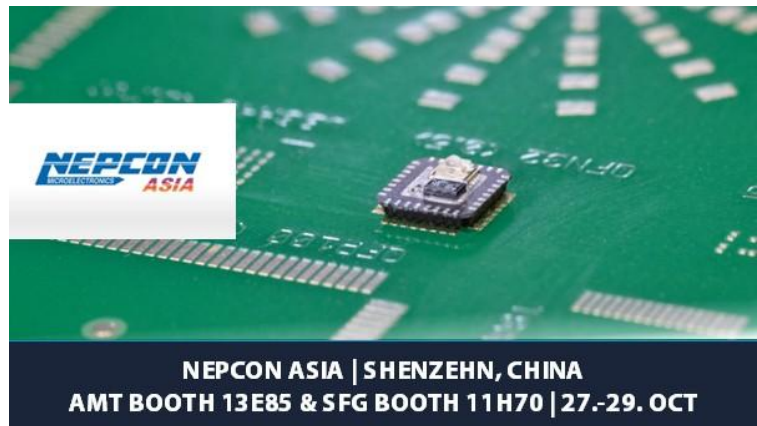


Essemtec to Showcase Advanced All-in-One Manufacturing Solutions for SMT and Advanced Packaging at NEPCON ASIA 2026

Visitors to Hall 1 Booth 11H70 and Hall 13 Booth 13E85 will discover Essemtec's latest innovations in SMT manufacturing, advanced packaging, high-speed solder paste jetting and precision dispensing technologies.

Essemtec, a global leader in adaptive SMT manufacturing solutions, will participate in NEPCON ASIA 2026, taking place from October 27-29, 2026, at the Shenzhen World Exhibition & Convention Center (Bao'an) in Shenzhen, China. Visitors are invited to explore Essemtec's latest innovations together with its local partners SFG Electronic Technology Co. at Hall 1, Booth 11H70 and AMT (American Tech) at Hall 13, Booth 13E85.



As electronics manufacturing continues to evolve toward greater product complexity, miniaturization and shorter product lifecycles, manufacturers are increasingly seeking solutions that improve flexibility while maintaining the highest levels of quality, repeatability and productivity.

At SFG's booth, visitors will experience live demonstrations of the PUMA Ultra All-in-One and FOX Ultra All-in-One platforms. These award-winning systems combine High-Speed Solder Paste Jetting, Epoxy Jetting, 2D Solder Paste Inspection (SPI), Placement and 2D Automated Optical Inspection (AOI) within a single adaptable manufacturing platform.

Designed for prototyping, New Product Introduction (NPI), high-mix production environments and advanced packaging applications, Essemtec's All-in-One solutions provide the flexibility required to rapidly adapt to changing products while maintaining exceptional placement accuracy and process repeatability.

Visitors will discover how High-Speed Solder Paste Jetting can eliminate the need for stencils in selected applications while enabling rapid product changeovers and greater manufacturing agility. The technology can also complement conventional screen printing

processes by reducing or eliminating the need for stepped stencils and supporting ultra-fine pitch applications where additional solder volume control is required.

At AMT's booth, Essemtec will showcase its SPIDER platform, a compact and highly flexible dispensing solution capable of supporting up to two dispensing valves.

Particular attention will be given to Essemtec's new 2K Precision Dispensing technology, developed for demanding meter-mix applications requiring highly accurate material preparation and deposition. The solution enables precise ratio control and repeatable dispensing results for two-component materials used in advanced electronics and industrial manufacturing processes.

By combining innovative All-in-One manufacturing platforms with advanced dispensing, Essemtec helps manufacturers improve productivity, accelerate time-to-market and increase manufacturing flexibility while reducing overall operating costs.

"Today's manufacturers need more than standalone equipment. They need intelligent and integrated production solutions that simplify manufacturing while remaining flexible enough to adapt to evolving products and process requirements," said Jacky Zhou (周杰), Country Sales Manager China. "At NEPCON ASIA 2026, we are excited to demonstrate how Essemtec's All-in-One platforms, advanced jetting technologies and new 2K Precision Dispensing solutions help customers address SMT, advanced packaging and precision dispensing challenges while improving quality, productivity and overall manufacturing efficiency."

Visitors are encouraged to meet with Essemtec and its local partners during the exhibition to discuss their manufacturing challenges and discover solutions tailored to their production requirements.

Visit Essemtec's Local Partners

SFG Electronic Technology Co. – Hall 1, Booth 11H70

- PUMA Ultra All-in-One
- FOX Ultra All-in-One
- High-Speed Solder Paste Jetting
- All-in-One Manufacturing Platform with Solder Paste Jetting, 2D SPI, Placement and 2D AOI

AMT (American Tech) – Hall 13, Booth 13E85

- SPIDER Dispensing Platform
- Up to Two Dispensing Valves
- Pre- and Post-Placement Dispensing Applications